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*Newberger, J.;*  
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*Martins, E.B.; Altemani, C.A.C.;*  
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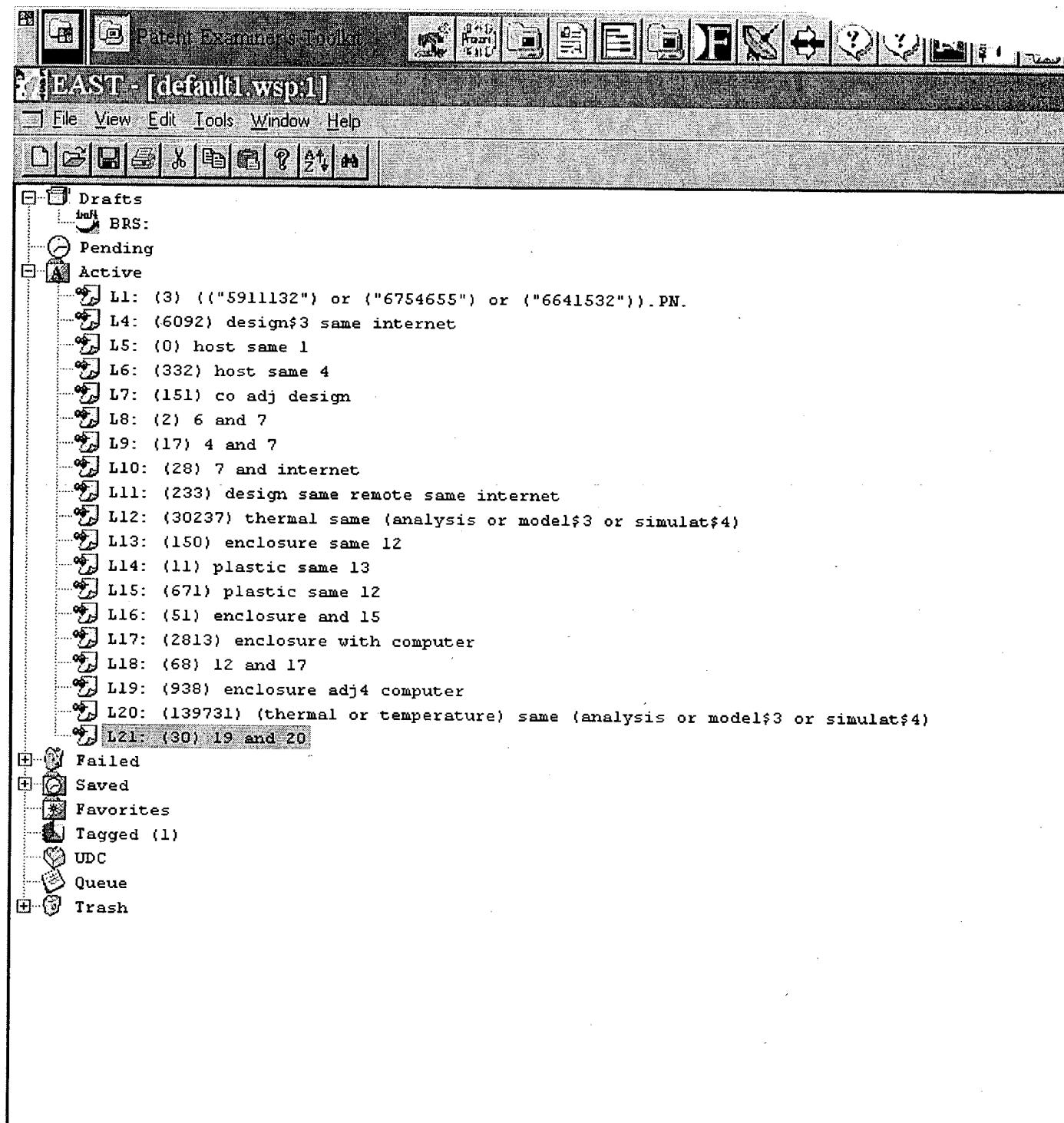
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